

# AJA sputter Orion-8-UHV



## Description

Sputtering is a precise thin film deposition technology. It offers excellent control over thickness and uniformity, making it ideal for optics, electronics, and surface applications. The system's compatibility with pressure-controlled reactive gases (Nitrogen and Oxygen) allows for compound film formation, while its scalability supports large-area substrate coating. The system offers a wide range of operation modes, including DC (up to 700W), pulse DC (up to 2kW), RF (up to 300W) , and RF bias for substrate (up to 50W), allowing to deposit layers with precise ferromagnetic properties.

## Specifications/Capabilities

Wafer size: up to 6" (152.4 mm)

Substrate rotation feature up to 20 rpm available

Deposition materials available: Cr, SiO<sub>2</sub>, Hf, AlTiCu, W-Ti 90/10, SiO, Si<sub>3</sub>N<sub>4</sub>, Tin oxide, ITO, Nb, Ti, TiN, Au, BN, C, In, Al, V, Ta<sub>2</sub>O<sub>5</sub>, W, Inconel. Suitable target dimensions: 2" dia, 0.25" thickness

Deposition range temperatures: up to 800°C (for up to 4"), up to 400°C (larger than 4" up to 6")

## Link

<https://www.ajaint.com/atc-orion-series-sputtering-systems.html>